L Number		Convert mout		
1 Number		Search Text (conduct\$3 near5 foil) or ((copper aluminum)	DB USPAT;	Time stamp 2003/10/03 20:27
1	33116	near5 (film sheet))	USPAT; US-PGPUB	2003/10/03 20:27
. 2	41998		USPAT;	2003/10/03 20:27
~	. 41550	aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	2003/10/03 20:27
3	29778	(((conduct\$3 near5 foil) or ((copper	USPAT:	2003/10/03 20:28
1	25770	aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	2003/10/03 20.28
	!) and (insulat\$3 dielectric)	U3-FGFUB	
4	19779	((((conduct\$3 near5 foil) or ((copper	USPAT;	2003/10/03 20:03
		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	2003/10/03 20:03
) and (insulat\$3 dielectric)) and etch\$3	00 10100	
5	17404		USPAT;	2003/10/03 20:28
! -		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	. 2003/10/03 20:20
I.	ļ	i) and (insulat\$3 dielectric)) and etch\$3)	00 10102	i
	i	and (trench recess open\$3 hole groove)		
່ 6	16468		USPAT;	2003/10/03 20:04
i		aluminum) near5 (film sheet))) and pattern\$3	US - PGPUB	,
) and (insulat\$3 dielectric)) and etch\$3)	:	
l		and (trench recess open\$3 hole groove)) and		
	ļ	(semiconductor wafer substrate)		
7	16445	((((((conduct\$3 near5 foil) or ((copper	USPAT;	2003/10/03 20:14
		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	
!) and (insulat\$3 dielectric)) and etch\$3)		
!	i	and (trench recess open\$3 hole groove)) and	1	
		(semiconductor wafer substrate)) and (copper	İ	
		Cu aluminum Al (iron?nickel (iron near3		
:	!	nickel)))		
8	11101	(((((((conduct\$3 near5 foil) or ((copper	USPAT;	2003/10/03 20:07
		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	
!) and (insulat\$3 dielectric)) and etch\$3)	1	
İ	i	and (trench recess open\$3 hole groove)) and		i
		(semiconductor wafer substrate)) and (copper		!
	ļ	Cu aluminum Al (iron?nickel (iron near3		!
		nickel)))) and (PR photoresist resist	:	
! _		photo?resist)		
9	5001		USPAT;	2003/10/03 20:28
		aluminum) near5 (film sheet))) and pattern\$3	US-PGPUB	
!	1) and (insulat\$3 dielectric)) and etch\$3)		
İ		and (trench recess open\$3 hole groove)) and		!
		(semiconductor wafer substrate)) and (copper		
	İ	Cu aluminum Al (iron?nickel (iron near3		
		nickel)))) and (PR photoresist resist photo?resist)) and resin		
10	117		i IIODam	2002/10/02 00 14
10	14/	((((((((((conduct\$3 near5 foil) or ((copper	USPAT;	2003/10/03 20:14
		aluminum) near5 (film sheet))) and pattern\$3)) and (insulat\$3 dielectric)) and etch\$3)	US-PGPUB	
ļ		and (Insulation dielectric) and etchion and and (trench recess open\$3 hole groove)) and	!	
		(semiconductor wafer substrate)) and (copper	İ	
		Cu aluminum Al (iron?nickel (iron near3		i
ļ		nickel)))) and (PR photoresist resist		
		photo?resist)) and resin) and ((electoless		!
		near3 plat\$3) electo?plat\$3 (electro near3		! i
		plat\$3))		1
11	13409	conduct\$3 near5 foil	USPAT;	2003/10/03 20:13
.=	-3.03		US-PGPUB	2003/10/03 20:13
12	10122	(conduct\$3 near5 foil) and (trench recess	USPAT;	2003/10/03 20:14
		open\$3 hole groove)	US-PGPUB	2000, 20, 00, 00, 20.14
13	9566	((conduct\$3 near5 foil) and (trench recess	USPAT;	2003/10/03 20:14
		open\$3 hole groove)) and (copper Cu aluminum	US-PGPUB	2005, 20, 05 20.14
	1	Al (iron?nickel (iron near3 nickel)))	35 13105	i
14	142		USPAT;	2003/10/03 20:15
		open\$3 hole groove)) and (copper Cu aluminum	US-PGPUB	2003/20/03 20:13
	: !	Al (iron?nickel (iron near3 nickel)))) and	1 20 13101	!
	1	((electoless near3 plat\$3) electo?plat\$3	1	i
	:	(electro near3 plat\$3))		1
15	6911 j	conductive near3 foil	USPAT;	2003/10/03 20:16
	1		US-PGPUB	
16	31 1	(conductive near3 foil) and (isolat\$3 near5	USPAT;	2003/10/03 20:16
	!	trench)	US-PGPUB	i = 100, 20, 00 20.10
17	65334	(conduct\$3 near5 foil) or ((copper aluminum)	EPO; JPO;	2003/10/03 20:27
		near5 (film sheet))	DERWENT;	1 23, 23, 23, 23, 24,
	<u></u> і		IBM TDB	

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18	8676	((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2003/10/03 20:28
1		aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	
I	į .		IBM_TDB	i
19	3516	(((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2003/10/03 20:28
1	İ	aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	!
Ĺ) and (insulat\$3 dielectric)	IBM_TDB	
20	1446	((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2003/10/03 20:28
		aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	i I
ļ	') and (insulat\$3 dielectric)) and (trench	IBM_TDB	Į.
		recess open\$3 hole groove)		!
21	271	(((((conduct\$3 near5 foil) or ((copper	EPO; JPO;	2003/10/03 20:29
1	ì	aluminum) near5 (film sheet))) and pattern\$3	DERWENT;	1
) and (insulat\$3 dielectric)) and (trench	IBM_TDB	!
		recess open\$3 hole groove)) and resin	L	<u> </u>